7--18. (New) The method measuring the thi

(New) The method according to claim 14, further comprising:

measuring the thickness of the first layer; and

automatically adjusting deviations between the measured thickness of the first

Yayer and the predetermined thickness.--

--19. (New) The method according to claim 14, wherein the predetermined thickness includes a range in at least one of a radial direction of the first substrate and a tangential direction of the first substrate.--

--20. (New) A method of producing optical storage disks, comprising: utilizing the method of claim 14.--

REMARKS

Claims 1-20 are pending. By this Amendment, the title is amended; the specification is amended; claims 1-12 are amended; and claims 13-20 are added. Reconsideration in view of the above amendments and the following remarks is respectfully requested.

The title was objected to. The title has been amended in accordance with the suggestion of the Office Action. Reconsideration and withdrawal of the objection to the title are respectfully requested.

The specification was objected to. The specification has been amended in accordance with the suggestion of the Office Action. Reconsideration and withdrawal of the objection to the specification are respectfully requested.

Claims 1-12 were rejected under 35 U.S.C. §112, second paragraph. In addition, claims 10 and 11 were rejected under 35 U.S.C. §101. Claims 1-12 have been amended in accordance with the suggestion of the Office Action. Reconsideration and withdrawal of the rejection of claims 1-12 under 35 U.S.C. §112, second paragraph, and the rejection of claims 10 and 11 under 35 U.S.C. §101 are respectfully requested.

Claims 1-6, 10 and 11 were rejected under 35 U.S.C. §103(a) over Kashiwagi et al. (U.S. Patent 5,938,891) in view of Japanese Patent Publication 3-178123 (JP '123). The rejection is respectfully traversed.

Claim 1, as amended, clearly recites a method including 1) providing a dosing pump for dosing viscous fluid, a dosing arm which is connected to the dosing pump and movable over the substrate, and a rotary drive for rotating the substrate and 2) regulating a layer thickness to a desired value, wherein control means controls at least one of the dosing pump, a position of the dosing arm and a rotary speed of the rotary drive in response to varying variables.

Kashiwagi et al. disclose a disk bonding system including an adhesive supplying section AS, N for supplying a liquid adhesive on a first disk DS1, a disk handling section R1, T1, T2 for mating the first disk DS1 with a second disk DS2, a spin coating section CH1, CH2, R2, EH for spreading the adhesive between the first and second disks DS1 and DS2 and a curing section UV1, T3, A1-4, CL for curing the adhesive.

The Office Action on page 7, lines 1-3, acknowledges that Kashiwaga et al. fail to disclose or suggest measuring and testing variables to control the thickness of the liquid adhesive. The Office Action then cites JP '123 as disclosing or suggesting applying a film onto a spinning substrate and measuring features such as the temperature of the substrate and coating material and adjusting the rotary drive for deviations of these measurements from a desired measurement.

The claimed invention measures certain variables that affect the layer of thickness, such as the temperatures of the substrates and the temperature of the viscous fluid. In response to the results of the measured values, certain functions are controlled, such as at least one of the dosing rate of the dosing pump, the position of the dosing arm with respect to the substrate, and the rotary speed of the rotary drive for rotating the substrate.

JP '123, on the other hand, discloses a method of obtaining a constant film thickness of a resist on a wafer 1. JP '123 uses the measurement of environmental temperature, environmental moisture, and the temperature of the wafer 1 and the coating liquid 30 to control the number of rotations of a spin coater. There is no disclosure or suggestion, however, by JP-123 of controlling the rotary speed of a rotary drive, as recited in claim 1. In addition, there is no disclosure or suggestion by JP '123 of controlling a dosing pump or of controlling the position of the supply tube 16 with respect to the wafer 1, as recited in claim 1. Accordingly, even assuming it would have been obvious to combine JP '123 with Kashiwagi et al., such a combination would not have resulted in the invention of claim 1.

Claims 2-6, 10 and 11 and new claim 13 recite additional features of the invention and are believed to be allowable at least for the reasons discussed above with respect to claim 1 and for the additional features recited therein.

Reconsideration and withdrawal of the rejection of claims 1-6, 10 and 11 under 35 U.S.C. §103(a) over Kashiwagi et al. in view of JP '123 are respectfully requested.

Claims 7-9 and 12 were rejected under 35 U.S.C. §103(a) over Kashiwagi et al. in view of JP '123 and further in view of Japanese Publication No. 7-29809 (JP '809). The rejection is respectfully traversed.

Claims 7-9 define additional features of claim 1 and are believed to be allowable at least for the reasons discussed above with respect to claim 1 and for the additional features recited therein.

Claim 12, as amended to be in independent form, is similar to claim 1 in that it recites a device for applying coatings or layers of viscous fluid onto planar substrates including a processor for controlling at least one of a dosing pump, a dosing arm connected to the dosing pump, and a rotary drive for rotating the substrates in response to varying variables and the measured thickness of the coating. It is also respectfully submitted that JP '809 fails to cure

the deficiencies of Kashiwagi et al. and JP '123 as it also fails to disclose or suggest controlling a dosing pump, a dosing arm connected to the dosing pump, and/or a rotary drive for rotating the substrates. Accordingly, even assuming it would have been obvious to combine JP '809 with Kashiwagi et al. and JP '123, such a combination would not have resulted in the invention of claim 12.

Reconsideration and withdrawal of the rejection of claims 7-9 and 12 under 35 U.S.C. §103(a) over Kashiwagi et al. in view of JP '123 and JP '809 are respectfully requested.

New claim 14 is similar to claim 1 in that it recites a method including controlling a thickness of a layer of viscous fluid by controlling at least one of a dosing pump, a position of a dosing arm with respect to the substrate, and a rotary speed of a rotary drive in response to variables. Accordingly, it is respectfully submitted that claim 14 is allowable at least for the reasons discussed above with respect to claim1 and for the additional features recited therein. In addition, new claims 15-20 recite additional features of the invention of claim 14 and are believed to be allowable at least for the reasons discussed above with respect to claims 1 and 14 and for the additional features recited therein.

In view of the above amendments and remarks, Applicants respectfully submit that all of the claims are allowable and that the entire application is in condition for allowance.

Should the Examiner believe that anything further is desirable to place the application in better condition for allowance, the Examiner is invited to contact the undersigned at the telephone number listed below.

Respectfully submitted,

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